Systems Integration

APOGEE® Open Processor with YORK AP Driver: YK Chiller

Table 1. YK Chiller.

Point	Type	Description	Range/Units
01	LAI	Leaving Chilled Water Temperature Setpoint	°C
02	LAI	Remote Current Setpoint	%
05	LDI	Start/Stop Status	On/Off
06	LDI	History Flag	On/Off
09	LAI	Leaving Chilled Water Temperature	°C
10	LAI	Entering Chilled Water Temperature	°C
11	LAI	Evaporator Pressure	kPa
12	LAI	Condenser Pressure	kPa
13	LAI	Oil Differential Pressure	kPa
14	LAI	Entering Condenser Water Temperature	°C
15	LAI	Leaving Condenser Water Temperature	°C
16	LAI	Motor Current	% FLA
17	LAI	Phase A Current	A
18	LAI	Phase B Current	A
19	LAI	Phase C Current	A
20	LAI	Phase A – C Line Voltage	V
21	LAI	Phase B – C Line Voltage	V
22	LAI	Phase C – A Line Voltage	V
23	LAI	Leaving Chilled Water Actual Setpoint	°C
24	LAI	Remote/Local Current Actual Setpoint	°C
25	LAI	Evaporator Saturation Temperature	°C
26	LAI	Condenser Saturation Temperature	°C
27	LAI	Discharge Temperature	°C
28	LAI	Oil Temperature	°C

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Table 1. YK Chiller.

Point	Type	Description	Range/Units
30	LAI	Accumulated Operating Time	hrs
31	LAI	Accumulated System Starts	Number of Starts
32	LAI	Low Oil Pressure Transducer	On/Off
33	LAI	High Oil Pressure Transducer	On/Off
34	LDI	Compressor Motor Status	On/Off
35	LDI	Online Solenoid Status	On/Off
36	LDI	Chilled Water Pump Status	On/Off
37	LDI	Start Switch Status	On/Off
38	LDI	Chilled Water Flow Switch Status	On/Off
54	LAI	Anti Recycle Time Left	sec
55	LAI	Operating Mode	—
56	LAI	Operating Code	—
57	LAI	Safety Shutdown Code	—
58	LAI	Cycling Shutdown Code	—
64	LAI	Proximity Sensor Actual Position	%
65	LAI	Proximity Sensor Reference Position	%
66	LAI	Drain Line Thermocouple Temperature	°C
83	LAO	Set Leaving Chilled Water Temperature Setpoint	°C
84	LAO	Set Remote Current Limit Setpoint	°C

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